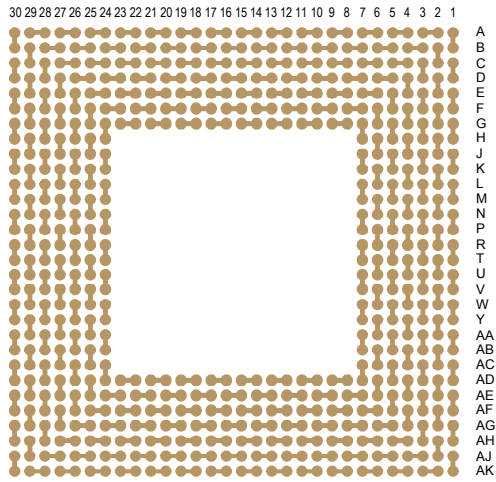


- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
 - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
 - 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm.
 - 4) SOLDER MASK DEFINED PAD OPENING: 0.22mm [8.7MIL].
 - 5) PAD Cu DIAMETER: 0.305mm [12 MIL].
 - 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
 - 7) DUMMY DIE IS OPTIONAL.
 - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
 - 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

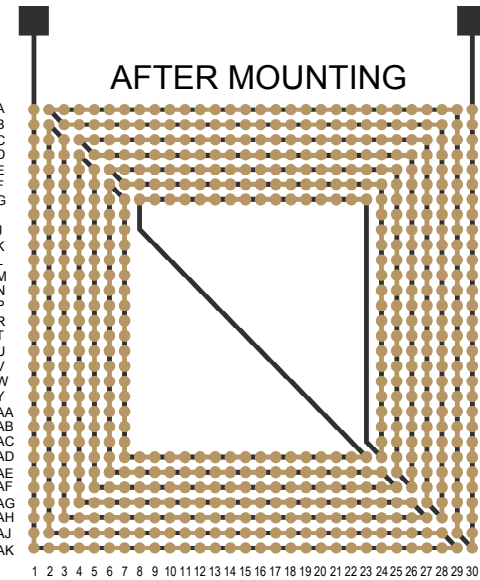
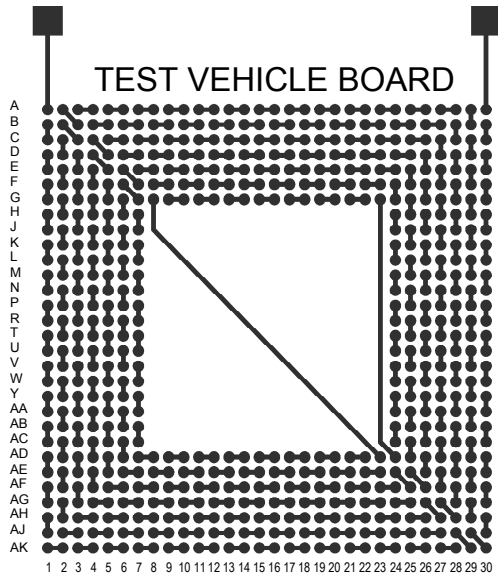
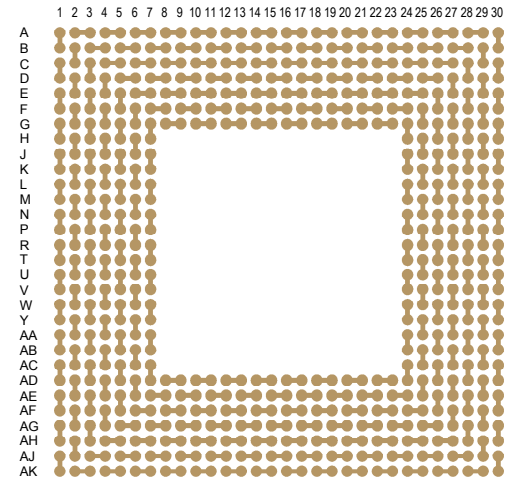
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA644T.4C-DC305D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA644T.4-DC305D	Sn63/Pb37	NO	NO	YES

APPROVALS		DATE				
DRAWN	T. Au	12/21/12				
ENG	M. Hart	12/21/12	SCALE		SIZE	DRAWING NO.
MFG					A	543051
QA						REV
CUST						A
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 2

BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.305mm [12MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.127mm [5 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.22mm [8.7 MIL].

TopLine®			
TITLE		BGA644T.4-DC305 DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
	A	543051	A
DO NOT SCALE DRAWING			SHEET 2 OF 2